

**IN THE SPECIFICATION**

*Please amend the paragraph [0049] at page 12, lines 10-11 in the specification as follows:*

[0049] Referring to FIG. [[2]] 3, the resin substrate formed by the manufacturing method of the embodiment will be explained.

*Please replace the abstract with the following new abstract:*

According to the invention, the method of manufacturing a module component comprises an inserting step of inserting a chip component in a first molding die; a primary molding step of filling the first molding die with resin with a first end electrode of the chip component exposed; a peeling step of peeling the first molding die at a side of inserting the chip component; a secondary molding step of filling a second molding die with resin with a second end electrode of the chip component; and a forming step of forming a circuit wiring on one side or both sides of a molded element molded with resin, wherein the chip component is disposed according to a specified rule, and the chip component is molded with the resin.